

DLP-7970ABP Hardware Update Overview

Ralph Jacobi, JD Crutchfield, and Josh Wyatt

NFC/RFID Applications

ABSTRACT

Texas Instruments and DLP Design, Inc. have released an updated design for the TRF7970A NFC/RFID BoosterPack™ plug-in module – the DLP-7970ABP.

This updated design includes new feature additions to support Ultra-Low Power (ULP) Wakeup and Special Direct Mode functionality.

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1 How Do I Know Which BoosterPack I Have?

The easiest way to determine if this document applies for a certain BoosterPack is to check the version number for the BoosterPack (highlighted by the light blue box in Figure 1). The modified design for the DLP-7970ABP applies for version 4.5 (v4.5) and newer. This guide does not apply for v4.4 or older. Alternatively, the new BoosterPack no longer covers the LaunchPad™ development kit buttons as seen in Figure 1 (highlighted by the green box) when attached to the top of a LaunchPad.



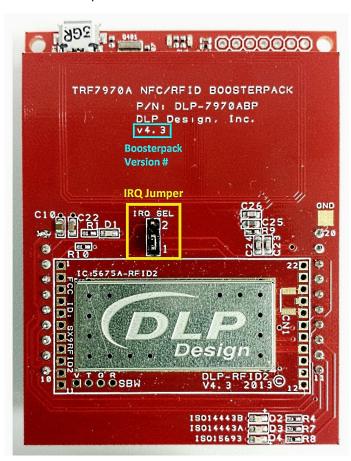


Figure 1. Comparison of New (Left, v4.5) and Old (Right, v4.3) DLP-7970ABP BoosterPack Boards



www.ti.com Hardware Changes

2 Hardware Changes

- The physical BoosterPack design has been modified to allow users much easier access to the push button inputs for TI LaunchPad boards.
- The IRQ header has been removed to make it easier for users to interact with the BoosterPack
 antenna when using other NFC/RFID devices such as personal handsets or other development kits. 0Ω resistors can be used instead to switch between the IRQ lines while providing a lower profile
 (highlighted by the yellow box in Figure 1).
- The revised pinout (see Table 1) enables developers to use additional features for the TRF7970A, such as using Special Direct Mode to read proprietary RFID tags.
- Some additional passive components have been added to support the addition of the ULP Wakeup feature.

3 New Features

ULP Wakeup

- The new BoosterPack design has been updated to support Ultra-Low Power NFC/RFID Card Presence Detection which can be used to minimize power consumption for reading from and writing to NFC/RFID tags.
- For details on how to use this new feature, see the application report NFC/RFID Reader Ultra-Low-Power Card Presence Detect With MSP430 and TRF79xxA (SLOA184).

Special Direct Mode

- The new BoosterPack pinout has been set up to give access to the I/O_2, I/O_3, and I/O_5 GPIO lines, which are required to use the Special Direct Mode (SDM) feature of the TRF7970A.
- SDM can be used to communicate with certain non-ISO standard RFID tags such as MIFARE® Classic tags, as well as other proprietary RFID protocols.
- For details on how to use this new feature, see the application report Using Special Direct Mode With the TRF7970A (SLOA214).



4 New DLP-7970ABP Pinout Table

To understand all of the pinout changes for the new DLP-7970ABP layout, refer to Table 1. For comparison, the pinout for the older versions of the DLP-7970ABP is provided in Table 2.

The tables have been colored to provide general guidelines for users who need to use a Logic State Analyzer (LSA), such as from Saleae, for debug purposes.

When using the Special Direct Mode functionality of the TRF7970A, be sure to attach LSA lines to the I/O_2, I/O_3, and I/O_5 pins for debugging.

The IRQ line defaults to pin 18 on all new BoosterPack kits. The routing of the IRQ line can be changed to pin 8 by resoldering the IRQ pads (boxed in yellow in Figure 1).

Table 1. Pinout for the New Version of the DLP-7970ABP

NEW BoosterPack Pinout Diagram						
TRF7970A Function	Header 1	Header 2	TRF7970A Function			
3VDC	1	20	GND			
ULP Wakeup ⁽¹⁾	2	19	1/0_3			
UART RX	3	18	IRQ (1) (default)			
UART TX	4	17	TEST / SBWTCK			
I/O_5	5	16	RST / NMI / SBWTDIO			
I/O_2	6	15	MOSI			
SPI_CLK	7	14	MISO			
IRQ (2)	8	13	ISO15693 LED			
SLAVE_SELECT	9	12	ISO14443A LED			
ENABLE	10	11	ISO14443B LED			

(1) ULP Wakeup requires a comparator to use.

Table 2. Pinout for Older Version of the DLP-7970ABP

OLD BoosterPack Pinout Diagram						
TRF7970A Function	Header 1		Header 2	TRF7970A Function		
3VDC	1		20	GND		
ANALOG IN	2		19	GPIO / PWM / XIN		
UART RX	3		18	IRQ (1)		
UART TX	4		17	TEST / SBWTCK		
GPIO	5		16	RST / NMI / SBWTDIO		
ANALOG IN	6		15	MOSI		
SPI_CLK	7		14	MISO		
IRQ (2)	8		13	ISO15693 LED		
SLAVE_SELECT	9		12	ISO14443A LED		
ENABLE	10		11	ISO14443B LED		

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